General Purpose PNP Epitaxial Planar Transistor

BCP53L3

Description

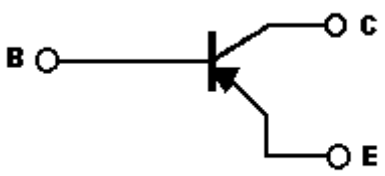
General purpose mainly intended for use in medium power industrial application and for audio amplifier output stage.

Features

- High collector current and low $V_{CE(SAT)}$
- Complement to BCP56L3
- Pb-free lead plating package

Symbol

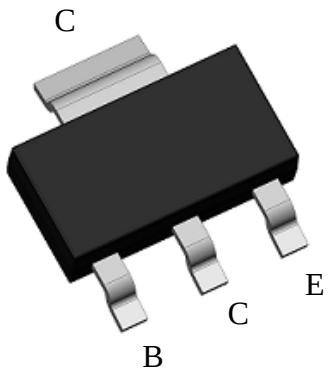
BCP53L3



B：Base
C：Collector
E：Emitter

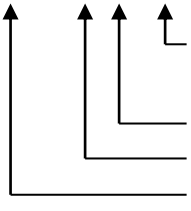
Outline

SOT-223



Ordering Information

Device	Package	Shipping
BCP53L3-XX-T3-G	SOT-223 (Pb-free lead plating package)	2500 pcs / tape & reel



Environment friendly grade : S for RoHS compliant products, G for RoHS compliant and green compound products

Packing spec, T3 : 2500 pcs / tape & reel, 13” reel

Product rank, zero for no rank products

Product name

Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Limits	Unit
Collector-Base Voltage	V_{CBO}	-100	V
Collector-Emitter Voltage	V_{CEO}	-80	V
Emitter-Base Voltage	V_{EBO}	-5	V
Collector Current(DC)	I_C	-1	A
Collector Current(Pulse)	I_{CP}	-1.5	A
Power Dissipation @T_C=25℃	Pd	2	W
Junction Temperature	Tj	150	°C
Storage Temperature	Tstg	-55~+150	°C

Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BV_{CBO}	-100	-	-	V	I_C=-100μA
BV_{CEO}	-80	-	-	V	I_C=-10mA
BV_{EBO}	-5	-	-	V	I_E=-10μA
I_{CBO}	-	-	-100	nA	V_{CB}=-80V
I_{EBO}	-	-	-100	nA	V_{EB}=-5V
*$V_{CE(sat)}$1	-	-0.16	-0.3	V	I_C=-500mA, I_B=-50mA
*$V_{CE(sat)}$2	-	-	-0.6	V	I_C=-700mA, I_B=-35mA
*$V_{BE(sat)}$	-	-	-1.2	V	I_C=-1A, I_B=-50mA
*$V_{BE(on)}$	-	-	-1.0	V	V_{CE}=-2V, I_C=-500mA
*h_{FE}1	100	-	-	-	V_{CE}=-2V, I_C=-5mA
*h_{FE}2	100	-	400	-	V_{CE}=-2V, I_C=-150mA
*h_{FE}3	50	-	-	-	V_{CE}=-2V, I_C=-500mA
f_T	-	125	-	MHz	V_{CE}=-10V, I_C=-50mA, f=100MHz
Cob	-	-	10	pF	V_{CB}=-10V, I_E=0A,f=1MHz

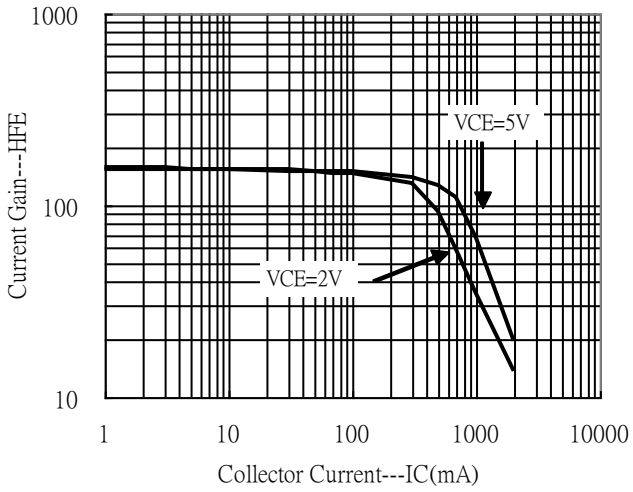
*Pulse Test: Pulse Width ≤380μs, Duty Cycle≤2%

Classification Of h_{FE} 2

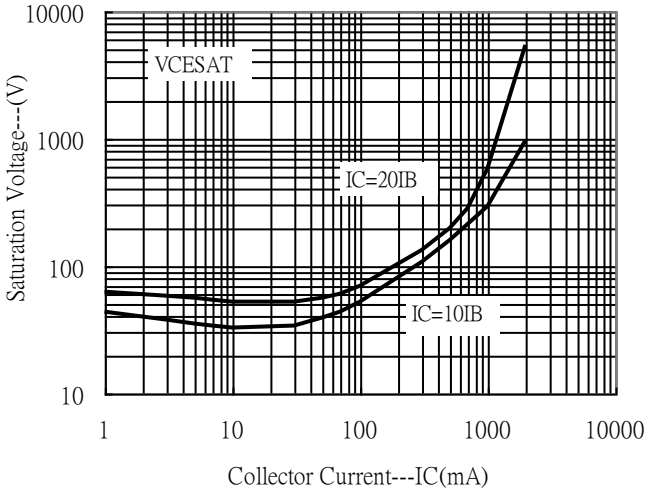
Rank	-16	-25
Range	100~250	160~400

Typical Characteristics

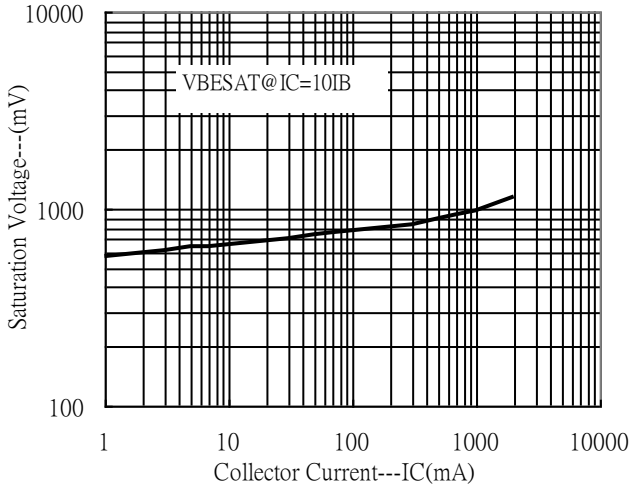
Current Gain vs Collector Current



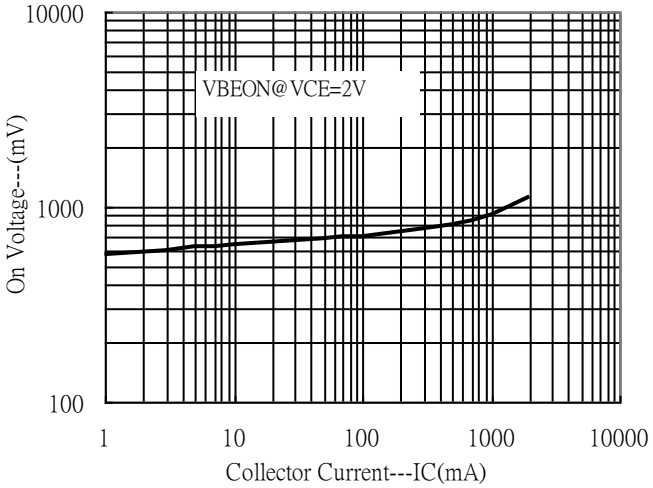
Saturation Voltage vs Collector Current



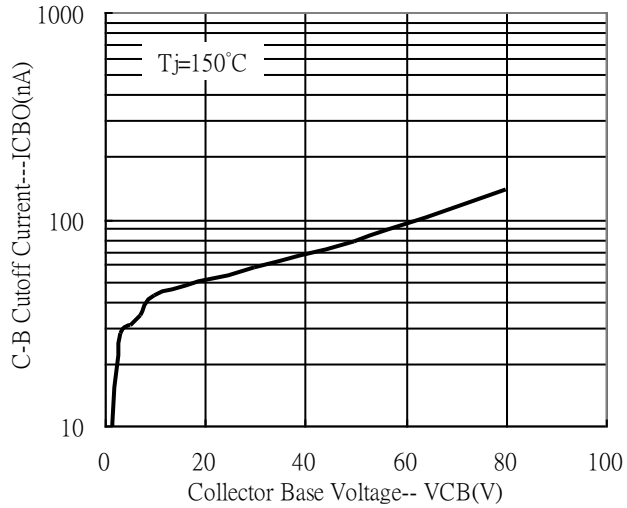
Saturation Voltage vs Collector Current



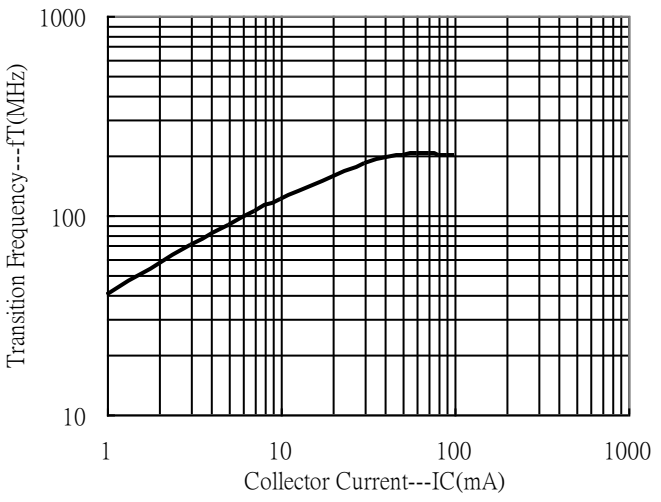
On Voltage vs Collector Current



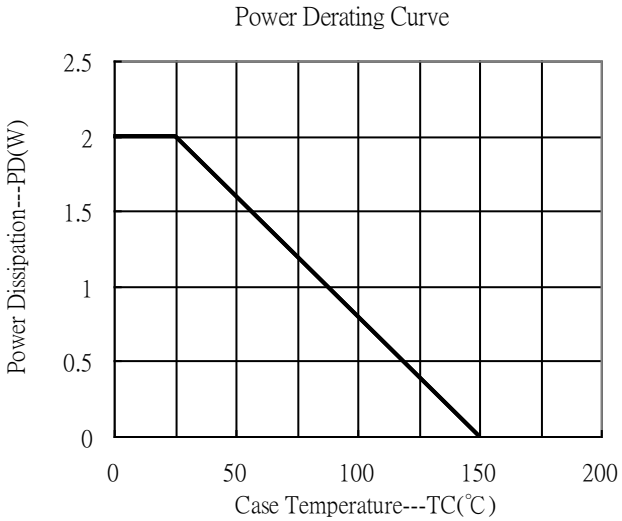
Typical Cutoff Current Characteristics



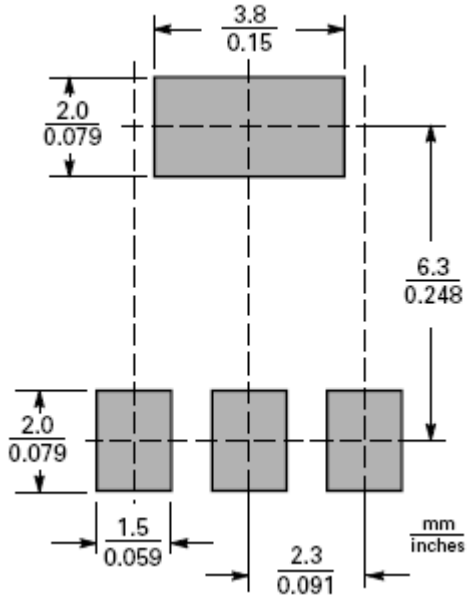
Transition Frequency vs Collector Current



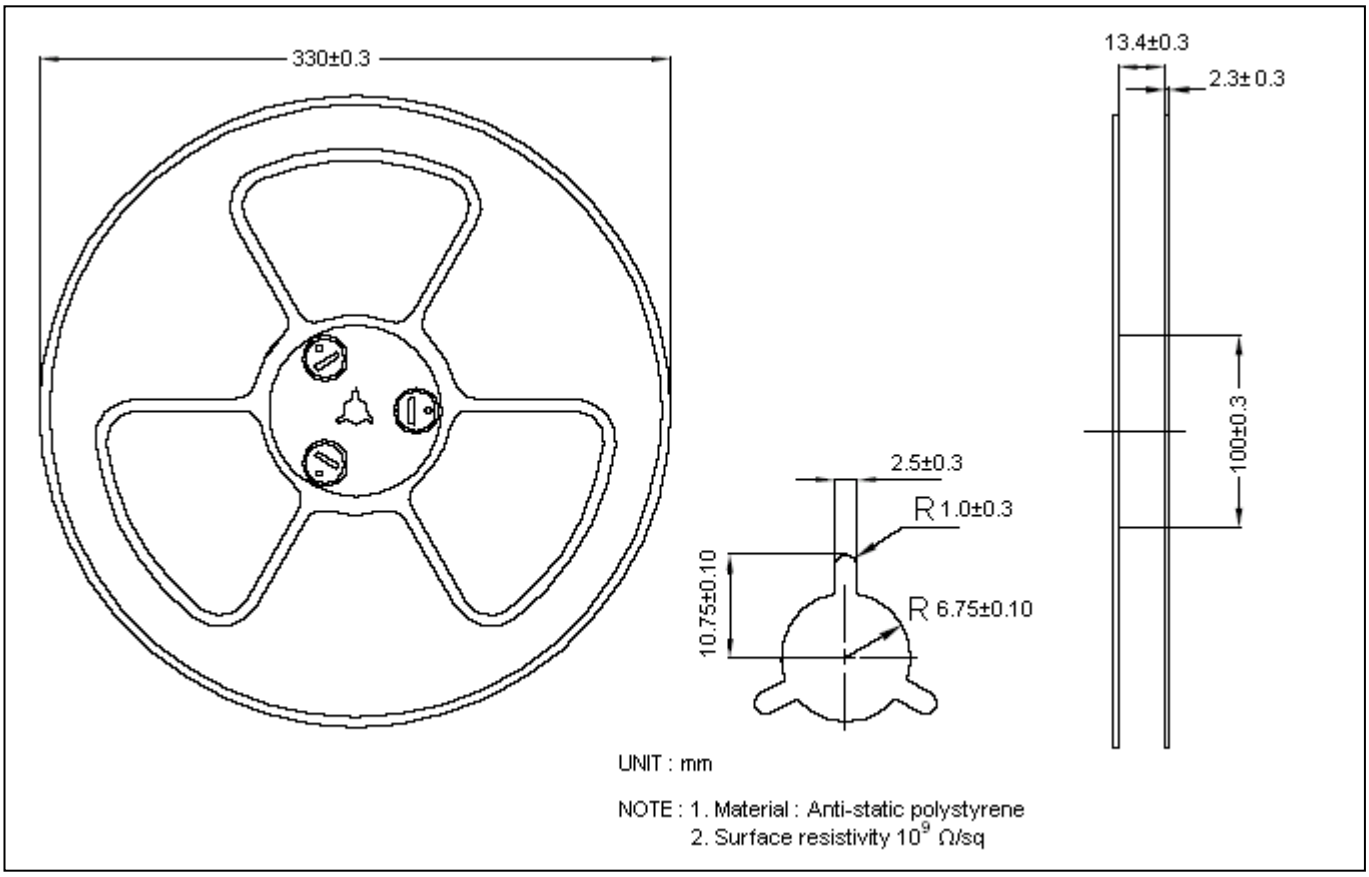
Typical Characteristics(Cont.)



Recommended soldering footprint



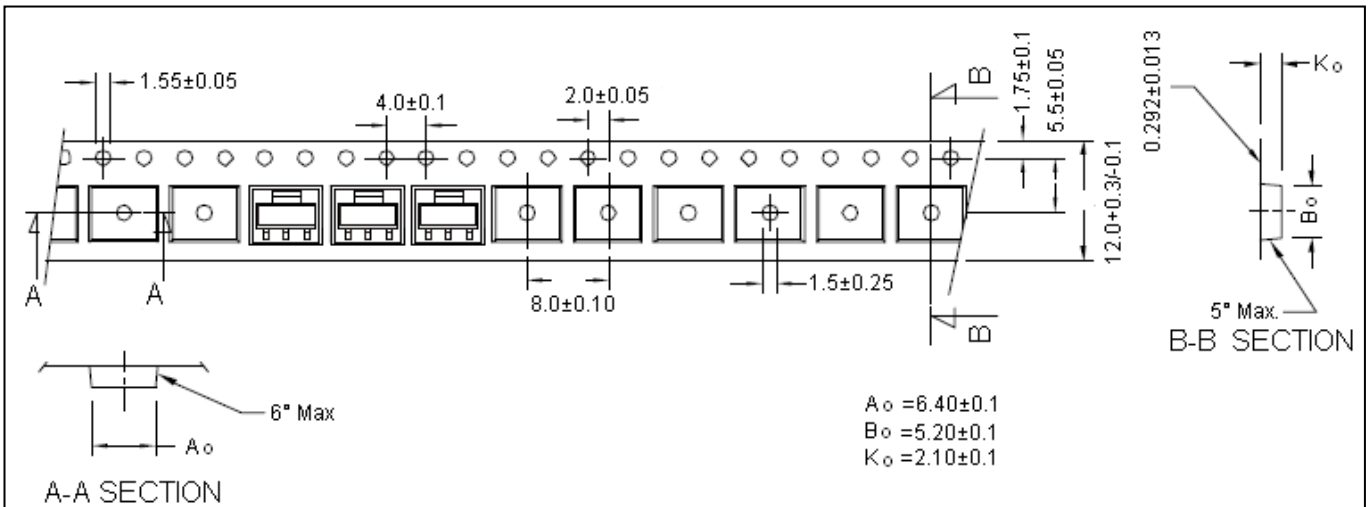
Reel Dimension



UNIT : mm

NOTE : 1. Material : Anti-static polystyrene
2. Surface resistivity 10^9 Ω/sq

Carrier Tape Dimension



Ao =6.40±0.1
Bo =5.20±0.1
Ko =2.10±0.1

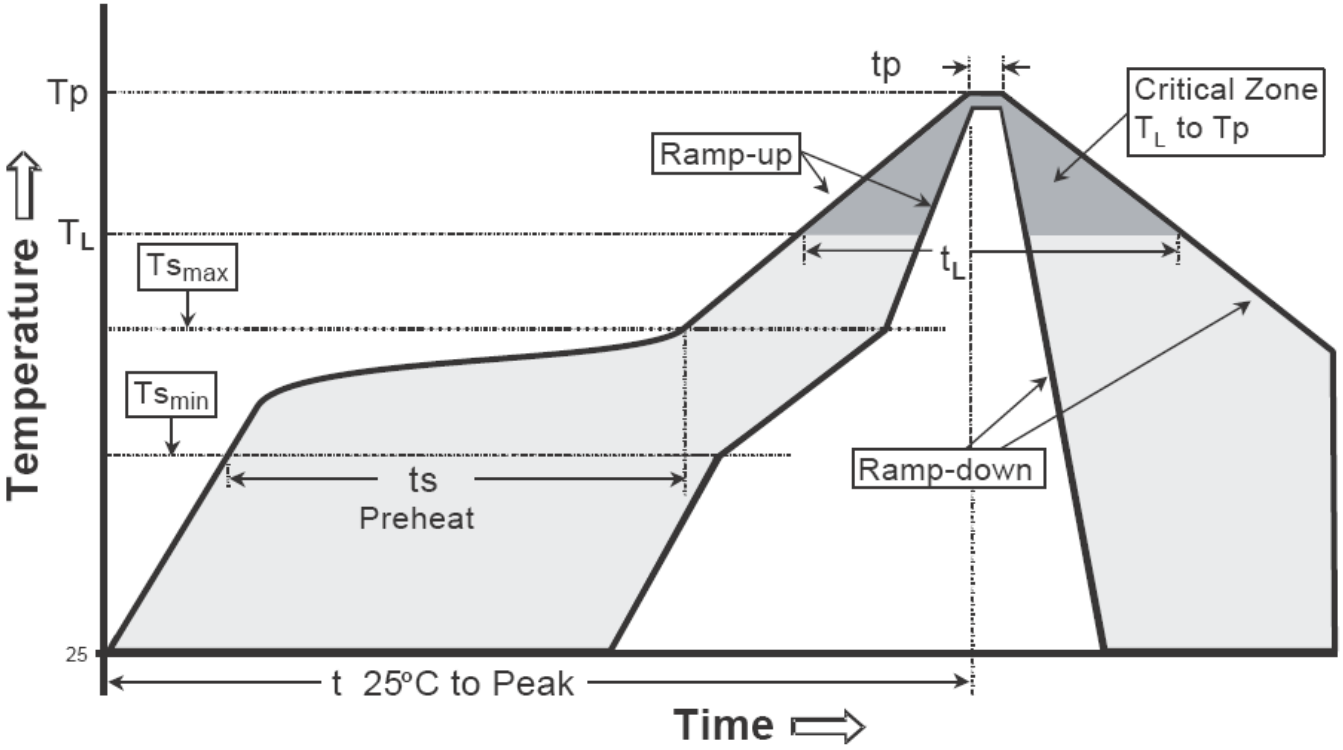
Notes:
1. 10 sprocket hole pitch cumulative tolerance ±0.2.
2. Camber not to exceed 1mm in 100mm.
3. Material: conductive black polystyrene
4. Ao & Bo measured on a plane 0.3mm above the bottom of the pocket.
5. Ko measured from a plane on the inside bottom of the pocket to the top surface of the carrier.
6. Pocket position relative to sprocket hole measured as true position of pocket, not pocket hole.

Uni : millimeter

Recommended wave soldering condition

Product	Peak Temperature	Soldering Time
Pb-free devices	260 +0/-5 °C	5 +1/-1 seconds

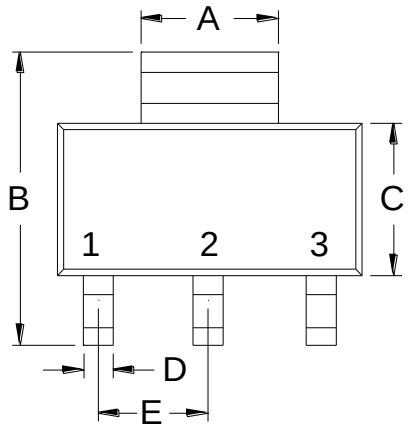
Recommended temperature profile for IR reflow

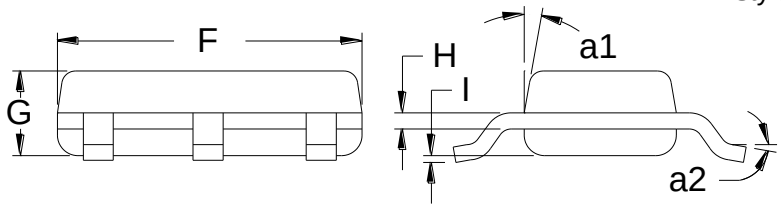


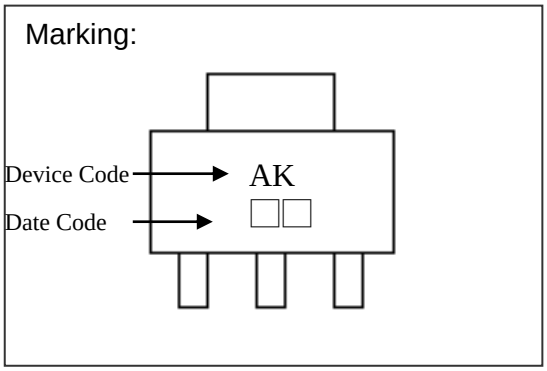
Profile feature	Sn-Pb eutectic Assembly	Pb-free Assembly
Average ramp-up rate (Tsmax to Tp)	3°C/second max.	3°C/second max.
Preheat −Temperature Min(T_S min) −Temperature Max(T_S max) −Time($t_{s\ min}$ to $t_{s\ max}$)	 100°C 150°C 60-120 seconds	 150°C 200°C 60-180 seconds
Time maintained above: −Temperature (T_L) − Time (t_L)	 183°C 60-150 seconds	 217°C 60-150 seconds
Peak Temperature(T_P)	240 +0/-5 °C	260 +0/-5 °C
Time within 5°C of actual peak temperature(tp)	10-30 seconds	20-40 seconds
Ramp down rate	6°C/second max.	6°C/second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

Note : All temperatures refer to topside of the package, measured on the package body surface.

SOT-223 Dimension







Style: Pin 1.Base 2.Collector 3.Emitter

3-Lead SOT-223 Plastic
Surface Mounted Package
CYStek Package Code: L3

*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1142	0.1220	2.90	3.10	G	0.0551	0.0709	1.40	1.80
B	0.2638	0.2874	6.70	7.30	H	0.0098	0.0138	0.25	0.35
C	0.1299	0.1457	3.30	3.70	I	0.0008	0.0039	0.02	0.10
D	0.0236	0.0315	0.60	0.80	a1	*13°	-	*13°	-
E	*0.0906	-	*2.30	-	a2	0°	10°	0°	10°
F	0.2480	0.2638	6.30	6.70					

Notes: 1.Controlling dimension: millimeters.
2.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
3.If there is any question with packing specification or packing method, please contact your local CYStek sales office.

Material:

- Lead: Pure tin plated.
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0